

# NCP361

## USB Positive Overvoltage Protection Controller with Internal PMOS FET and Overcurrent Protection

The NCP361 disconnects systems at its output when wrong VBUS operating conditions are detected at its input. The system is positive over-voltage protected up to +20 V.

Thanks to an integrated PMOS FET, no external device is necessary, reducing the system cost and the PCB area of the application board.

The NCP361 is able to instantaneously disconnect the output from the input if the input voltage exceeds the overvoltage threshold (5.675 V). Thanks to an overcurrent protection, the integrated PMOS is turning off when the charge current exceeds integrated limit (see options in ordering information).

The NCP361 provides a negative going flag ( $\overline{\text{FLAG}}$ ) output, which alerts the system that voltage, current or overtemperature faults have occurred.

In addition, the device has ESD-protected input (15 kV Air) when bypassed with a 1  $\mu\text{F}$  or larger capacitor.

### Features

- Overvoltage Protection up to 20 V
- On-chip PMOS Transistor
- Overvoltage Lockout (OVLO)
- Undervoltage Lockout (UVLO)
- Overcurrent Protection
- Alert  $\overline{\text{FLAG}}$  Output
- $\overline{\text{EN}}$  Enable Pin
- Thermal Shutdown
- Compliance to IEC61000-4-2 (Level 4)
  - 8 kV (Contact)
  - 15 kV (Air)
- ESD Ratings: Machine Model = B  
Human Body Model = 2
- 6 Leads UDFN 2x2 mm Package
- 5 Leads TSOP-5 3x3 mm Package
- This is a Pb-Free Device

### Applications

- USB Devices
- Mobile Phones
- Peripheral
- Personal Digital Applications
- MP3 Players
- Set Top Boxes



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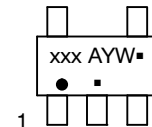


6 PIN UDFN  
CASE 517AB

### MARKING DIAGRAMS

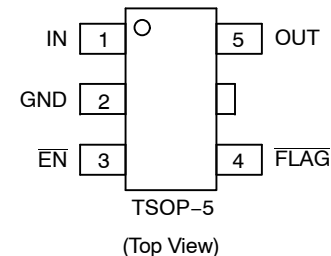
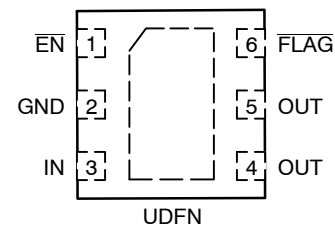


TSOP-5  
CASE 483



xxx = Specific Device Code  
M = Date Code  
A = Assembly Location  
Y = Year  
W = Work Week  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

### PIN CONNECTIONS



### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

# NCP361

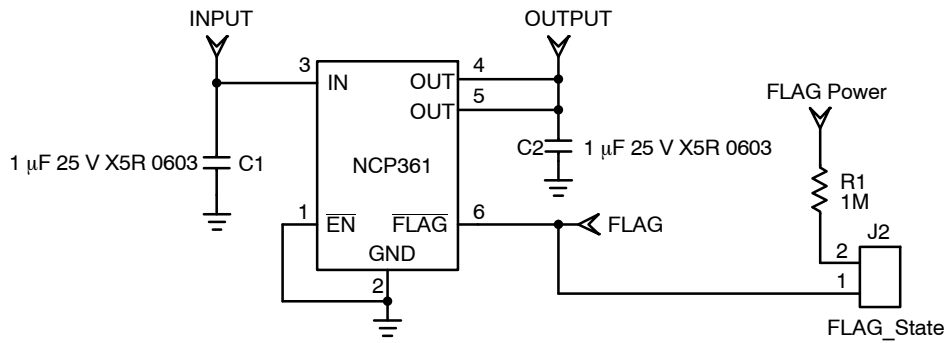


Figure 1. Typical Application Circuit (UDFN Pinout)

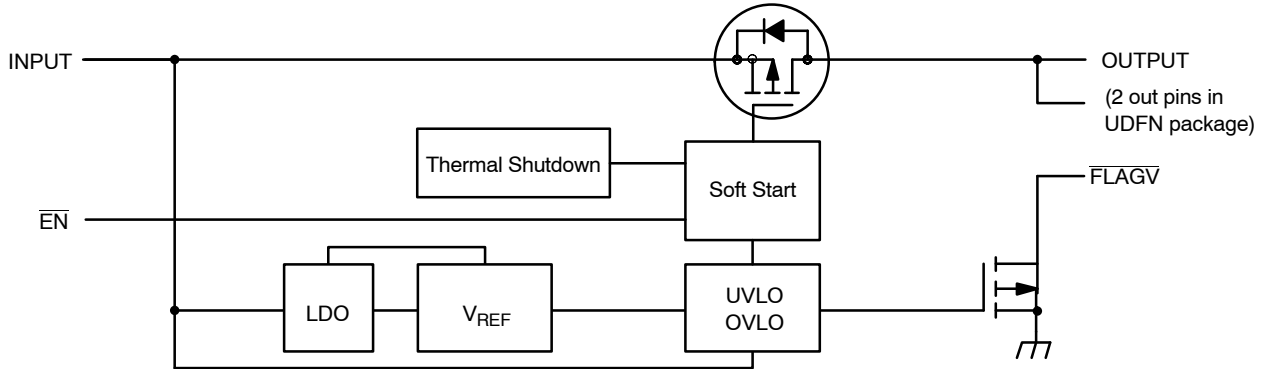


Figure 2. Functional Block Diagram

## PIN FUNCTION DESCRIPTION (UDFN Package)

Pin No.	Name	Type	Description
1	$\overline{\text{EN}}$	INPUT	Enable Pin. The device enters in shutdown mode when this pin is tied to a high level. In this case the output is disconnected from the input. To allow normal functionality, the $\overline{\text{EN}}$ pin shall be connected to GND or to a I/O pin. This pin does not have an impact on the fault detection.
2	GND	POWER	Ground
3	IN	POWER	Input Voltage Pin. This pin is connected to the VBUS. A 1 $\mu\text{F}$ low ESR ceramic capacitor, or larger, must be connected between this pin and GND.
4, 5	OUT	OUTPUT	Output Voltage Pin. The output is disconnected from the VBUS power supply when the input voltage is above OVLO threshold or below UVLO threshold. A 1 $\mu\text{F}$ capacitor must be connected to these pins. The two OUT pins must be hardwired to common supply.
6	$\overline{\text{FLAG}}$	OUTPUT	Fault Indication Pin. This pin allows an external system to detect a fault on VBUS pin. The $\overline{\text{FLAG}}$ pin goes low when input voltage exceeds OVLO threshold. Since the $\overline{\text{FLAG}}$ pin is open drain functionality, an external pull up resistor to $V_{\text{CC}}$ must be added.

## PIN FUNCTION DESCRIPTION (TSOP-5 Package)

Pin No.	Name	Type	Description
1	IN	POWER	Input Voltage Pin. This pin is connected to the VBUS. A 1 $\mu\text{F}$ low ESR ceramic capacitor, or larger, must be connected between this pin and GND.
2	GND	POWER	Ground
3	$\overline{\text{EN}}$	INPUT	Enable Pin. The device enters in shutdown mode when this pin is tied to a high level. In this case the output is disconnected from the input. To allow normal functionality, the $\overline{\text{EN}}$ pin shall be connected to GND or to a I/O pin. This pin does not have an impact on the fault detection.
4	$\overline{\text{FLAG}}$	OUTPUT	Fault Indication Pin. This pin allows an external system to detect a fault on VBUS pin. The $\overline{\text{FLAG}}$ pin goes low when input voltage exceeds OVLO threshold. Since the $\overline{\text{FLAG}}$ pin is open drain functionality, an external pull up resistor to $V_{\text{CC}}$ must be added.
5	OUT	OUTPUT	Output Voltage Pin. The output is disconnected from the VBUS power supply when the input voltage is above OVLO threshold or below UVLO threshold. A 1 $\mu\text{F}$ capacitor must be connected to this pin.

NOTE: Pin out provided for concept purpose only and might change in the final product

# NCP361

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Minimum Voltage (IN to GND)	$V_{min_{in}}$	-0.3	V
Minimum Voltage (All others to GND)	$V_{min}$	-0.3	V
Maximum Voltage (IN to GND)	$V_{max_{in}}$	21	V
Maximum Voltage (All others to GND)	$V_{max}$	7.0	V
Maximum DC Current from Vin to Vout (PMOS) (Note 1)	$I_{max}$	600	mA
Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	305 240	°C/W
		TSOP-5 UDFN	
Operating Ambient Temperature Range	$T_A$	-40 to +85	°C
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Junction Operating Temperature	$T_J$	150	°C
ESD Withstand Voltage (IEC 61000-4-2) Human Body Model (HBM), Model = 2 (Note 2) Machine Model (MM) Model = B (Note 3)	$V_{esd}$	15 Air, 8.0 Contact 2000 200	kV V V
Moisture Sensitivity	MSL	Level 1	-

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. With minimum PCB area. By decreasing  $R_{\theta JA}$ , the current capability increases. See PCB recommendation page 9.
2. Human Body Model, 100 pF discharged through a 1.5 k $\Omega$  resistor following specification JESD22/A114.
3. Machine Model, 200 pF discharged through all pins following specification JESD22/A115.

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## ELECTRICAL CHARACTERISTICS

(Min/Max limits values ( $-40^{\circ}\text{C} < T_A < +85^{\circ}\text{C}$ ) and  $V_{in} = +5.0\text{ V}$ . Typical values are  $T_A = +25^{\circ}\text{C}$ , unless otherwise noted.)

Characteristic	Symbol	Conditions	Min	Typ	Max	Unit
Input Voltage Range	$V_{in}$		1.2		20	V
Undervoltage Lockout Threshold	UVLO	$V_{in}$ falls down UVLO threshold	2.85	3.0	3.15	V
Uvoltage Lockout Hysteresis	UVLO <sub>hyst</sub>		50	70	90	mV
Overvoltage Lockout Threshold	OVLO	$V_{in}$ rises up OVLO threshold	5.43	5.675	5.9	V
Overvoltage Lockout Hysteresis	OVLO <sub>hyst</sub>		50	100	125	mV
$V_{in}$ versus $V_{out}$ Dropout	$V_{drop}$	$V_{in} = 5\text{ V}$ , I charge = 500 mA		150	200	mV
Overcurrent Limit	$I_{lim}$	$V_{in} = 5\text{ V}$	550	750	950	mA
Supply Quiescent Current	$I_{dd}$	No Load, $V_{in} = 5.25\text{ V}$		20	35	$\mu\text{A}$
Standby Current	$I_{std}$	$V_{in} = 5\text{ V}$ , EN = 1.2 V		26	37	$\mu\text{A}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20\text{ V}$ , $V_{GS} = 0\text{ V}$		0.08		$\mu\text{A}$
FLAG Output Low Voltage	$V_{olflag}$	$V_{in} > \text{OVLO}$ Sink 1 mA on FLAG pin			400	mV
FLAG Leakage Current	FLAG <sub>leak</sub>	FLAG level = 5 V		5.0		nA
$\overline{\text{EN}}$ Voltage High	$V_{ih}$	$V_{in}$ from 3.3 V to 5.5 V	1.2			V
$\overline{\text{EN}}$ Voltage Low	$V_{il}$	$V_{in}$ from 3.3 V to 5.5 V			0.55	V
EN Leakage Current	EN <sub>leak</sub>	EN = 5.5 V or GND		170		nA

## TIMINGS

Start Up Delay	$t_{on}$	From $V_{in} > \text{UVLO}$ to $V_{out} = 0.8 \times V_{in}$ , See Fig 3 & 9		4.0	15	ms
FLAG going up Delay	$t_{start}$	From $V_{in} > \text{UVLO}$ to FLAG = 1.2 V, See Fig 3 & 10		3.0		$\mu\text{s}$
Output Turn Off Time	$t_{off}$	From $V_{in} > \text{OVLO}$ to $V_{out} \leq 0.3\text{ V}$ , See Fig 4 & 11 $V_{in}$ increasing from 5 V to 8 V at 3 V/ $\mu\text{s}$ . No output capacitor.		0.7	1.5	$\mu\text{s}$
Alert Delay	$t_{stop}$	From $V_{in} > \text{OVLO}$ to FLAG $\leq 0.4\text{ V}$ , See Fig 4 & 12 $V_{in}$ increasing from 5 V to 8 V at 3 V/ $\mu\text{s}$		1.0		$\mu\text{s}$
Disable Time	$t_{dis}$	From $\overline{\text{EN}}$ 0.4 to 1.2V to $V_{out} \leq 0.3\text{ V}$ , See Fig 5 & 13 $V_{in} = 4.75\text{ V}$ . No output capacitor.		3.0		$\mu\text{s}$
Thermal Shutdown Temperature	$T_{sd}$			150		$^{\circ}\text{C}$
Thermal Shutdown Hysteresis	$T_{sdhyst}$			30		$^{\circ}\text{C}$

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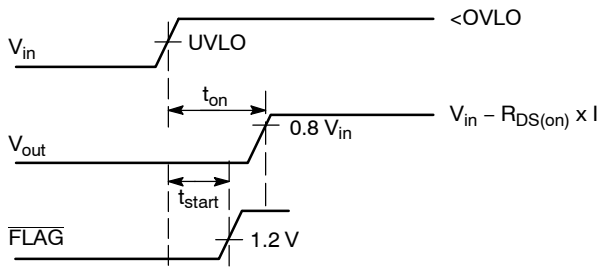


Figure 3. Start Up Sequence

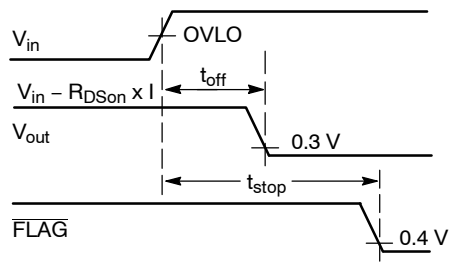


Figure 4. Shutdown on Over Voltage Detection

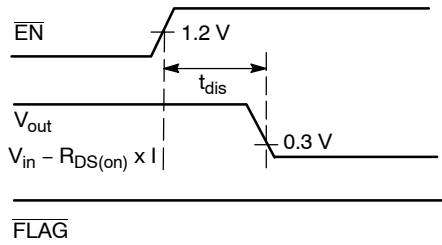


Figure 5. Disable on  $\overline{EN} = 1$

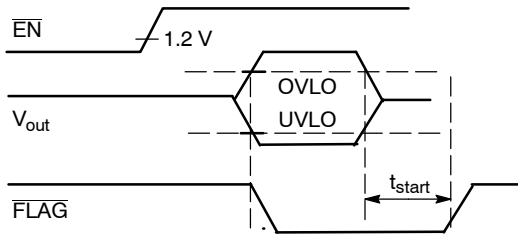


Figure 6.  $\overline{FLAG}$  Response with  $\overline{EN} = 1$

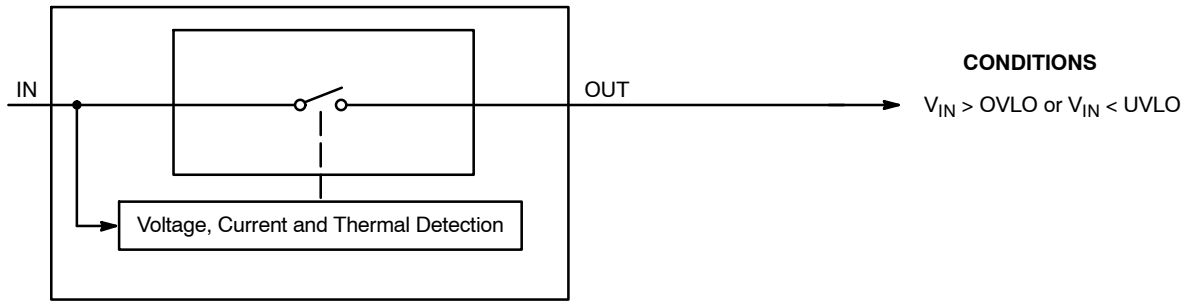


Figure 7.

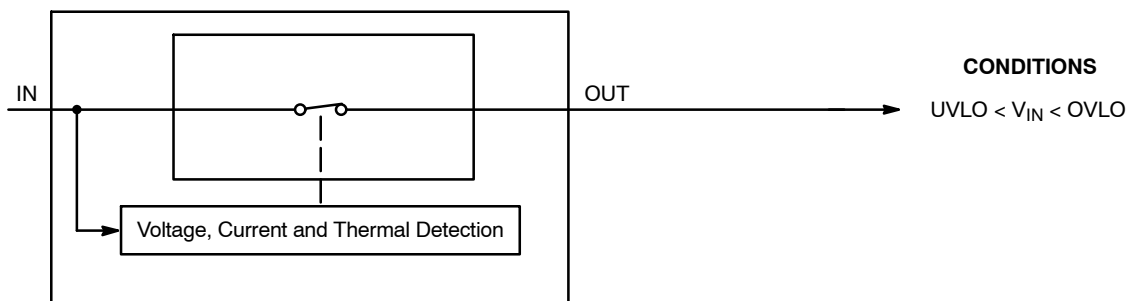


Figure 8.

TYPICAL OPERATING CHARACTERISTICS

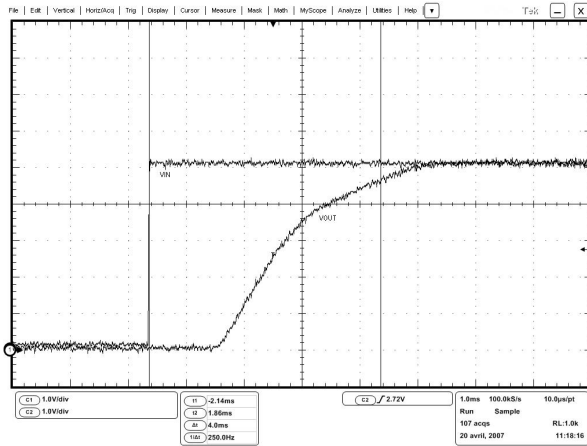


Figure 9. Start Up. Vin=Ch1, Vout=Ch2

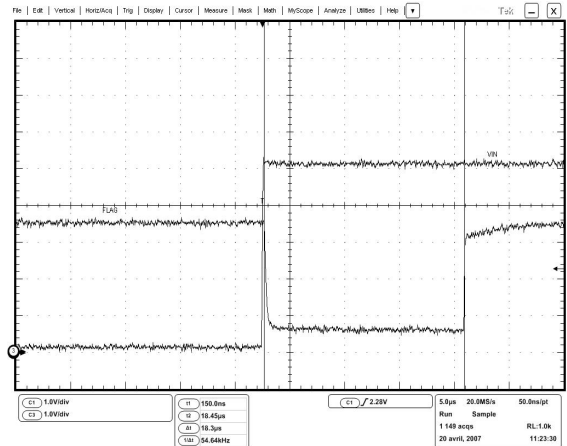


Figure 10. FLAG Going Up Delay. Vin=Ch1, FLAG=Ch3

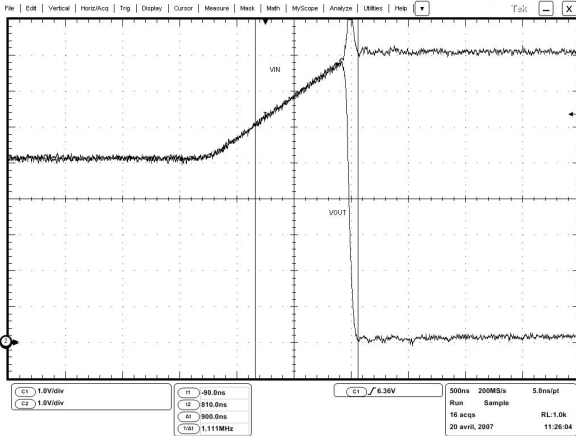


Figure 11. Output Turn Off time. Vin=Ch1, Vout=Ch2

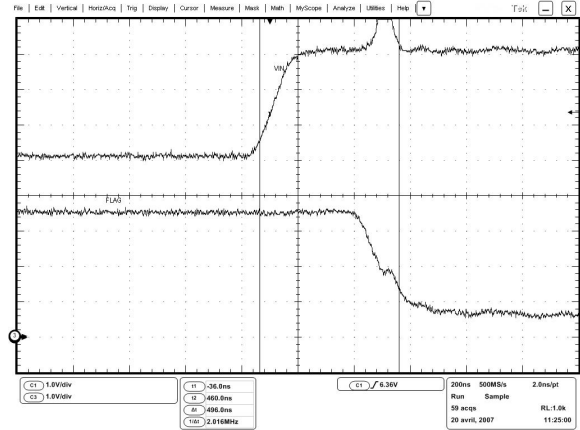


Figure 12. Alert Delay. Vout=Ch1, FLAG=Ch3

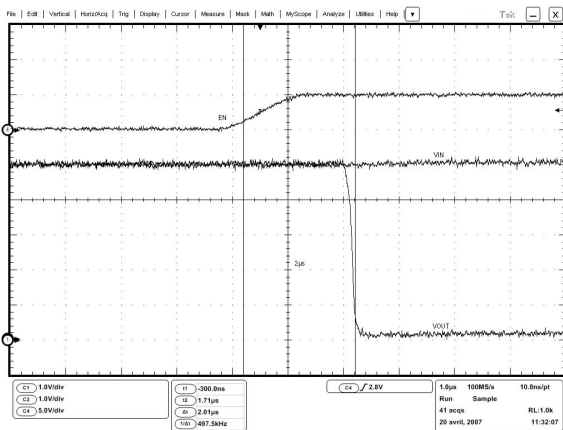


Figure 13. Disable Time. EN=Ch4, Vin=Ch1, Vout=Ch2

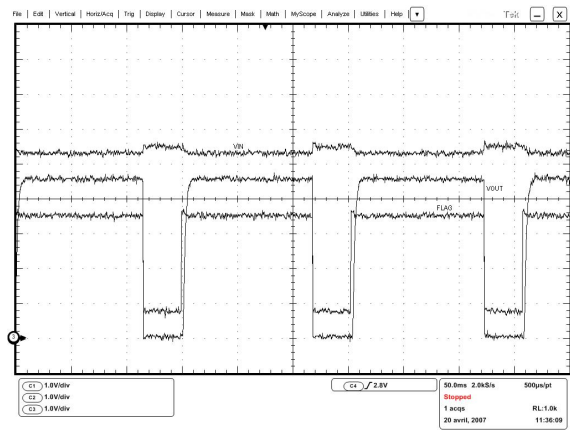


Figure 14. Thermal Shutdown. Vin=Ch1, Vout=Ch2, FLAG=Ch3

# NCP361

## TYPICAL OPERATING CHARACTERISTICS

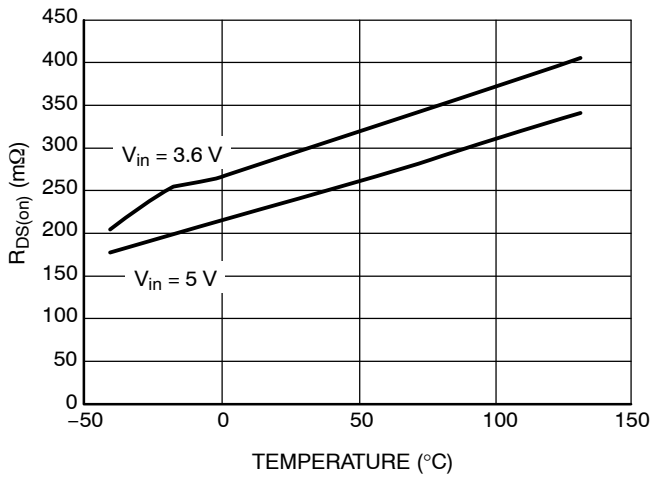


Figure 15.  $R_{DS(on)}$  vs. Temperature  
(Load = 500 mA)

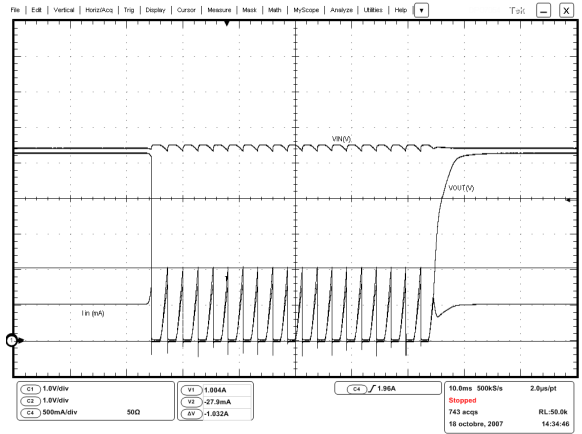


Figure 16. Output Short Circuit

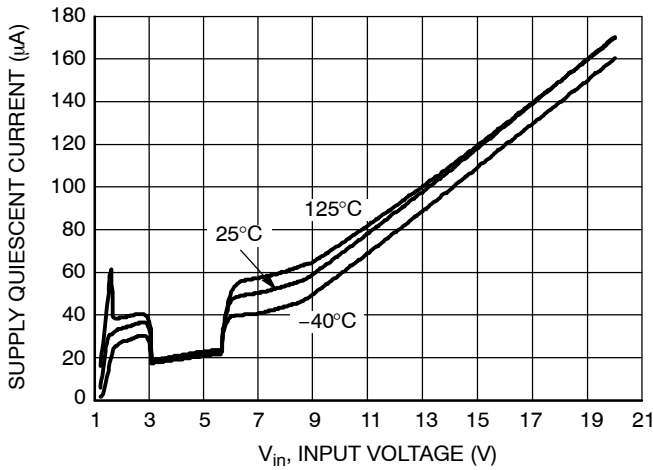


Figure 17. Quiescent Current vs. Input Voltage

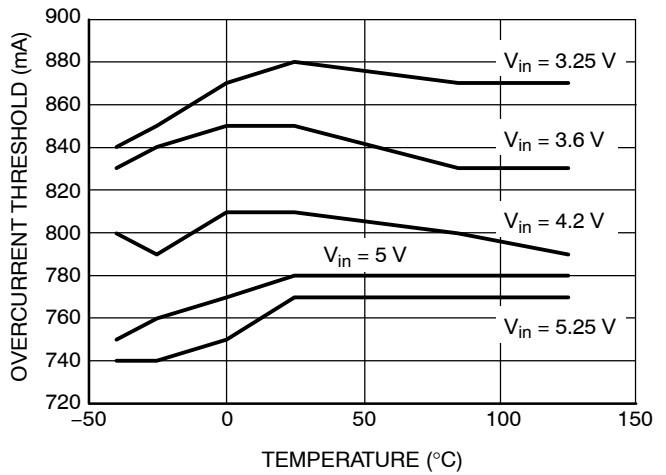


Figure 18. Overcurrent Protection Threshold vs. Temperature

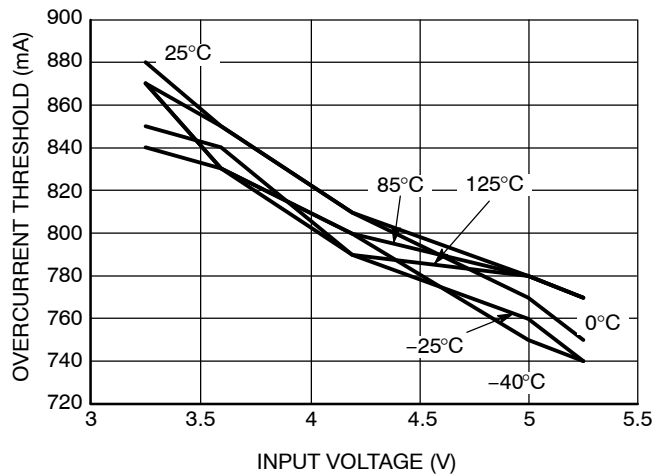


Figure 19. Overcurrent Protection Threshold vs. Input Voltage





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## PCB Recommendations

The NCP361 integrates a 500 mA rated PMOS FET, and the PCB rules must be respected to properly evacuate the heat out of the silicon. The UDFN PAD1 must be connected to ground plane to increase the heat transfer if necessary from an application standpoint. Of course, in any case, this pad shall be not connected to any other potential.

By increasing PCB area, the  $R_{\theta JA}$  of the package can be decreased, allowing higher charge current to fill the battery.

Taking into account that internal bondings (wires between package and silicon) can handle up to 1 A (higher than thermal capability), the following calculation shows

two different example of current capability, depending on PCB area:

- With 305°C/W (without PCB area), allowing DC current is 500 mA
- With 260°C/W (200 mm<sup>2</sup>), the charge DC current allows with a 85°C ambient temperature is:  

$$I = \sqrt{(T_J - T_A) / (R_{\theta JA} \times R_{DS(on)})}$$

$$I = 625 \text{ mA}$$

In every case, we recommend to make thermal measurement on final application board to make sure of the final Thermal Resistance.

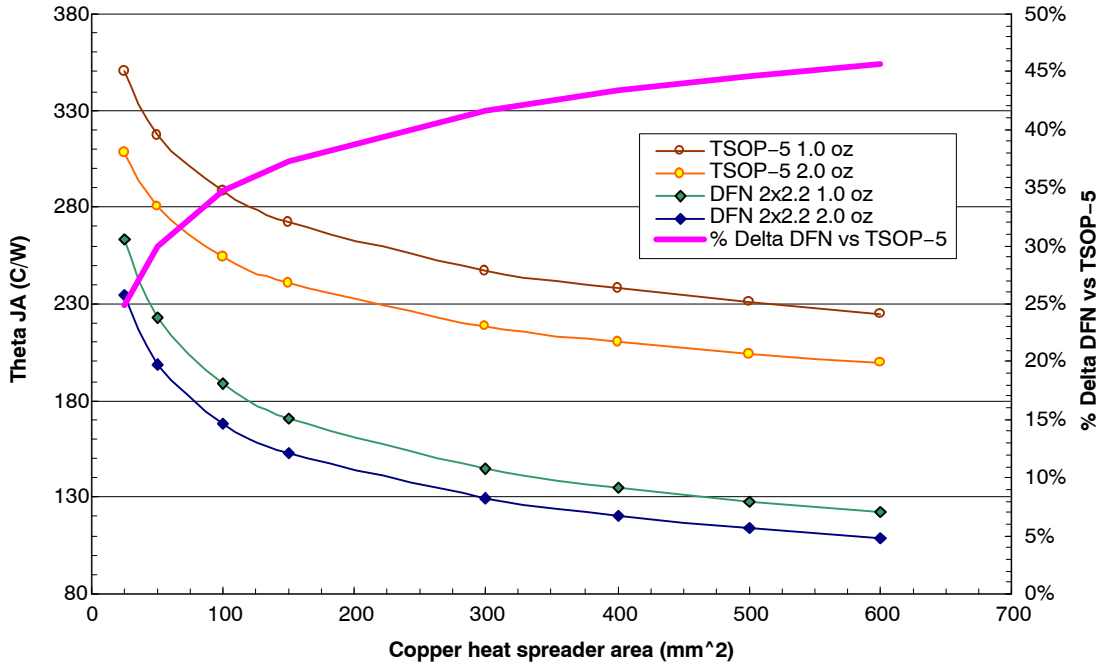


Figure 23. Thermal Resistance of UDFN 2x2 and TSOP Packages as a Function of PCB Area and Thickness

# NCP361

## ORDERING INFORMATION

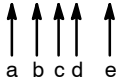
Device	Marking	Package	Shipping†
NCP361MUTBG	AD	UDFN6 (Pb-Free)	3000 / Tape & Reel
NCP361SNT1G	ACD	TSOP-5 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## SELECTION GUIDE

The NCP361 can be available in several undervoltage and overvoltage thresholds versions. Part number is designated as follows:

**NCP361xxxxTxG**



Code	Contents
a	Overcurrent Threshold –: 750 mA
b	Package MU: UDFN SN: TSOP-5
c	UVLO Typical Threshold –: 3.00 V
d	OVLO Typical Threshold –: 5.675 V
e	Tape & Reel Type B: = 3000 1: = 3000

NOTE: Additional current limit, UVLO and OVLO can be available.  
Please contact your ON Semiconductor representative for availability.

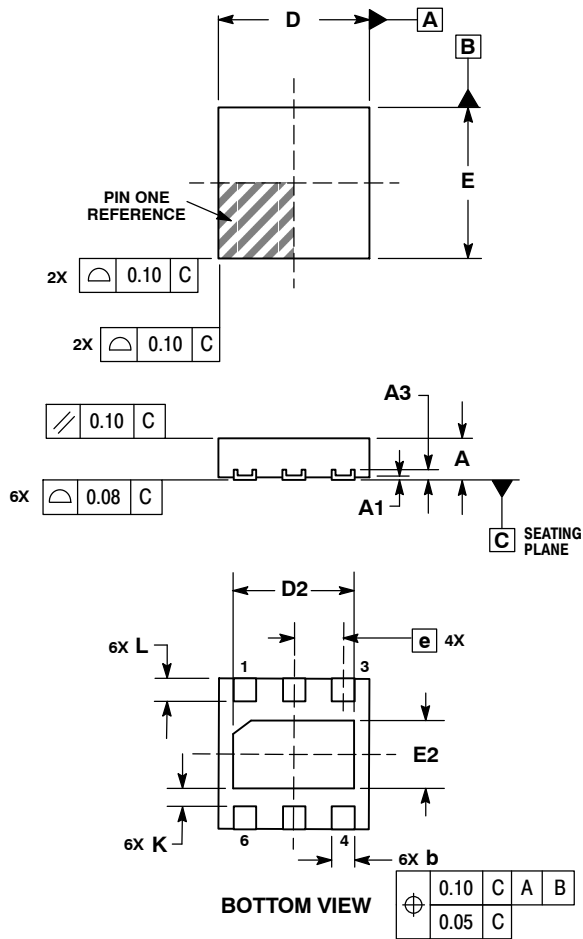
# NCP361

## PACKAGE DIMENSIONS

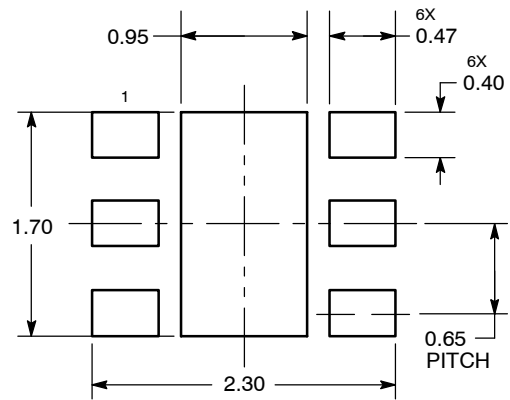
UDFN6 2x2, 0.65P  
CASE 517AB-01  
ISSUE B

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.25	0.35
D	2.00 BSC	
D2	1.50	1.70
E	2.00 BSC	
E2	0.80	1.00
e	0.65 BSC	
K	0.20	---
L	0.25	0.35



### SOLDERING FOOTPRINT\*



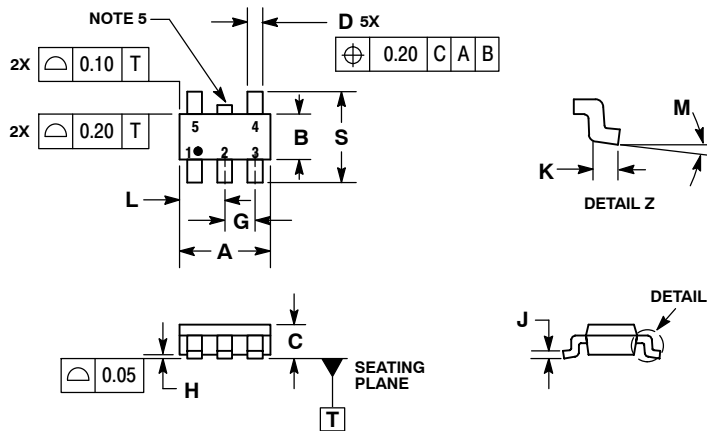
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# NCP361

## PACKAGE DIMENSIONS

### TSOP-5 CASE 483-02 ISSUE G

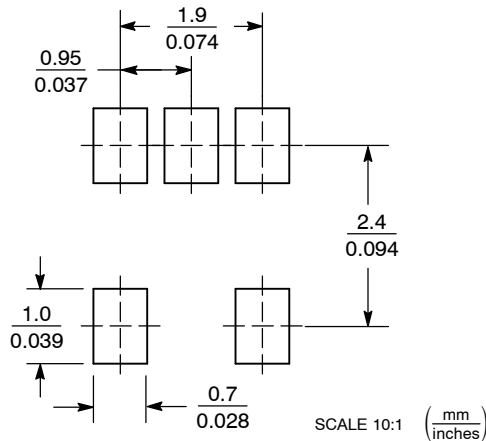


#### NOTES:


1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

DIM	MILLIMETERS	
	MIN	MAX
A	3.00	BSC
B	1.50	BSC
C	0.90	1.10
D	0.25	0.50
G	0.95	BSC
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
L	1.25	1.55
M	0°	10°
S	2.50	3.00

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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